

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)  
 Contact Info: [ti.com/support](http://ti.com/support)  
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB  
 Created on: 08/25/2022

Details for "TP563060MDSCTEP"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package   Pins	Package body size (mm)	Total device mass (mg)*
TP563060MDSCTEP	NIPDAU	Level-2-260C-1 YEAR	TI MALAYSIA A/T	DSC   10	3x3x0.7	21.8

\*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
<b>Bond Wire</b>							
Other Nonferrous Metals and Alloys	Germanium	7440-56-4	0.000003	0.001063	11	0.000014	0
Precious Metals	Gold	7440-57-5	0.282269	99.99752	999975	1.294693	12947
Precious Metals	Palladium	7440-05-3	0.000002	0.000709	7	0.000009	0
Precious Metals	Silver	7440-22-4	0.000002	0.000709	7	0.000009	0
Sub-Total			0.282276	100	1000000	1.294725	12947
<b>Die Attach Adhesive</b>							
Precious Metals	Silver	7440-22-4	0.506648	80	800000	2.32386	23239
Thermoplastics	Epoxy	85954-11-6	0.126662	20	200000	0.580965	5810
Sub-Total			0.63331	100	1000000	2.904825	29048
<b>Lead Frame</b>							
Copper and Its Alloys	Copper	7440-50-8	11.557663	99.249996	992500	53.011934	530119
Other Nonferrous Metals and Alloys	Chromium	7440-47-3	0.030277	0.26	2600	0.138873	1389
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.029113	0.250004	2500	0.133534	1335
Zinc and Its Alloys	Zinc	7440-66-6	0.027948	0.24	2400	0.12819	1282
Sub-Total			11.645001	100	1000000	53.412531	534125
<b>Lead Frame Plating</b>							
Nickel and Its Alloys	Nickel	7440-02-0	0.199384	95.120055	951201	0.914522	9145
Precious Metals	Gold	7440-57-5	0.001635	0.780009	7800	0.007499	75
Precious Metals	Palladium	7440-05-3	0.008594	4.099937	40999	0.039418	394
Sub-Total			0.209613	100	1000000	0.961439	9614
<b>Mold Compound</b>							
Other Inorganic Materials	Fused Silica	60676-86-0	6.898994	90.499998	905000	31.643855	316439
Other Plastics and Rubber	Carbon Black	1333-86-4	0.038116	0.5	5000	0.174828	1748
Thermoplastics	Epoxy	85954-11-6	0.686088	9.000002	90000	3.146904	31469
Sub-Total			7.623198	100	1000000	34.965587	349656
<b>Semiconductor Device</b>							
Ceramics / Glass	Doped Silicon	7440-21-3	1.408604	100	1000000	6.460893	64609
Sub-Total			1.408604	100	1000000	6.460893	64609
<b>Total</b>			21.802002			100	1000000

Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component. The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component. See Glossary of Terms for more details.

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI's or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

For an explanation of the methods used to determine material weights, See Product Content Methodology

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former IIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

For additional information, please contact TI customer support.

Signature: [\(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality

For further environmental statements, please go to [www.ti.com/ecoinfo](http://www.ti.com/ecoinfo)

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**RoHS:** Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

**RoHS Exempt:** Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

**Green:** Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet J5709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.